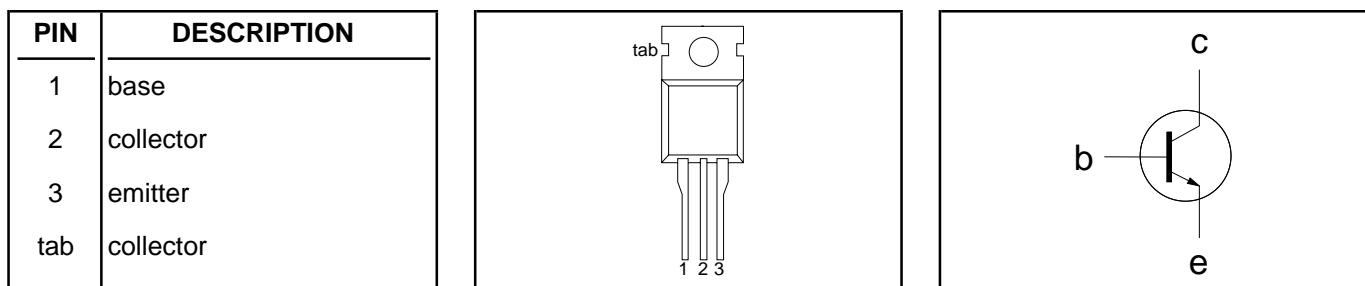


**Silicon Diffused Power Transistor****BUJ303B****GENERAL DESCRIPTION**

High-voltage, high-speed planar-passivated npn power switching transistor in a TO220AB envelope intended for use in high frequency electronic lighting ballast applications, converters, inverters, switching regulators, motor control systems, etc.

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_{CESM}$	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1050	V
$V_{CBO}$	Collector-Base voltage (open emitter)		-	1050	V
$V_{CEO}$	Collector-emitter voltage (open base)		-	400	V
$I_C$	Collector current (DC)		-	5	A
$I_{CM}$	Collector current peak value		-	10	A
$P_{tot}$	Total power dissipation	$T_{mb} \leq 25 \text{ }^{\circ}\text{C}$	-	100	W
$V_{CEsat}$	Collector-emitter saturation voltage	$I_C = 3 \text{ A}; I_B = 1 \text{ A}$	0.25	1.5	V
$h_{FEsat}$	DC current gain	$I_C = 3 \text{ A}; V_{CE} = 1.5 \text{ V}$	10.5	-	V
$t_f$	Fall time	$I_C = 2.5 \text{ A}, I_{B1} = 0.5 \text{ A}$	300	-	ns

**PINNING - TO220AB****PIN CONFIGURATION****SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CESM}$	Collector to emitter voltage	$V_{BE} = 0 \text{ V}$	-	1050	V
$V_{CEO}$	Collector to emitter voltage (open base)		-	400	V
$V_{CBO}$	Collector to base voltage (open emitter)		-	1050	V
$I_C$	Collector current (DC)		-	5	A
$I_{CM}$	Collector current peak value		-	10	A
$I_B$	Base current (DC)		-	2	A
$I_{BM}$	Base current peak value		-	4	A
$P_{tot}$	Total power dissipation	$T_{mb} \leq 25 \text{ }^{\circ}\text{C}$	-	100	W
$T_{stg}$	Storage temperature		-65	150	$^{\circ}\text{C}$
$T_j$	Junction temperature		-	150	$^{\circ}\text{C}$

**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$R_{th,j-mb}$	Junction to mounting base		-	1.25	K/W
$R_{th,j-a}$	Junction to ambient	in free air	60	-	K/W

## Silicon Diffused Power Transistor

BUJ303B

**STATIC CHARACTERISTICS** $T_{mb} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CES}, I_{CBO}$ $I_{CES}$	Collector cut-off current <sup>1</sup>	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$ $V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$ $T_j = 125^\circ\text{C}$	-	-	1.0 2.0	mA mA
$I_{CEO}$	Collector cut-off current <sup>1</sup>	$V_{CEO} = V_{CEOMmax}(400\text{V})$	-	-	0.1	mA
$I_{EBO}$ $V_{CEO_sust}$ $V_{CEsat}$	Emitter cut-off current Collector-emitter sustaining voltage Collector-emitter saturation voltage	$V_{EB} = 9 \text{ V}; I_c = 0 \text{ A}$ $I_c = 300 \text{ mA}; L = 25 \text{ mH}$ $I_c = 3 \text{ A}; I_B = 1 \text{ A}$ $I_c = 1 \text{ A}; I_B = 0.2 \text{ A}$	400	- 0.25	0.1 1.5 0.5	mA V V
$V_{BEsat}$ $h_{FE}$	Base-emitter saturation voltage DC current gain	$I_c = 3 \text{ A}; I_B = 1 \text{ A}$ $I_c = 10 \text{ mA}; V_{CE} = 5 \text{ V}$ $I_c = 800 \text{ mA}; V_{CE} = 3 \text{ V}$	- 10 23	1.0 - 31	1.5 - 40	V
$h_{FEsat}$	DC current gain	$I_c = 3 \text{ A}; V_{CE} = 1.5 \text{ V}$	-	10.5	-	

**DYNAMIC CHARACTERISTICS** $T_{mb} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$t_{on}$ $t_s$ $t_f$	Switching times (resistive load) Turn-on time Turn-off storage time Turn-off fall time	$I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; I_{Boff} = -1 \text{ A};$ $V_{CC} = 250 \text{ V};$	1 2.5 0.3	- -	$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
$t_s$ $t_f$	Switching times (inductive load) Turn-off storage time Turn-off fall time	$I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; -V_{BB} = 5 \text{ V};$ $L_C = 300 \mu\text{H}; L_B = 1 \mu\text{H}; V_{CC} = 350 \text{ V}$	2 200	- -	$\mu\text{s}$ $ns$
$t_s$ $t_f$	Switching times (inductive load) Turn-off storage time Turn-off fall time	$I_{Con} = 2.5 \text{ A}; I_{Bon} = 0.5 \text{ A}; -V_{BB} = 5 \text{ V};$ $L_C = 300 \mu\text{H}; L_B = 1 \mu\text{H}; V_{CC} = 350 \text{ V};$ $T_j = 100^\circ\text{C}$	3 300	- -	$\mu\text{s}$ $ns$

<sup>1</sup> Measured with half sine-wave voltage (curve tracer).

## Silicon Diffused Power Transistor

BUJ303B

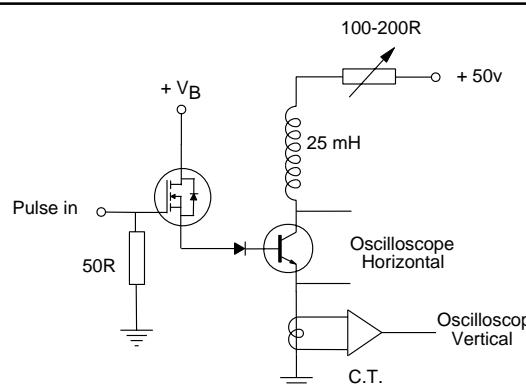
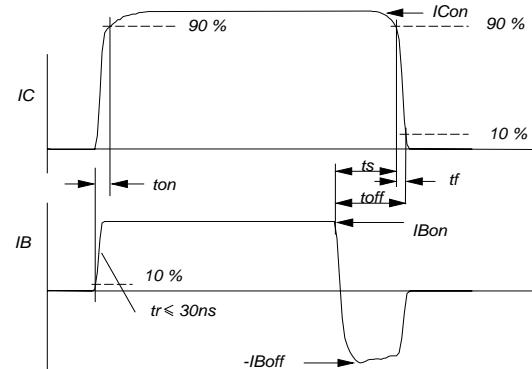
Fig.1. Test circuit for  $V_{CEO_sust}$ .

Fig.4. Switching times waveforms with resistive load.

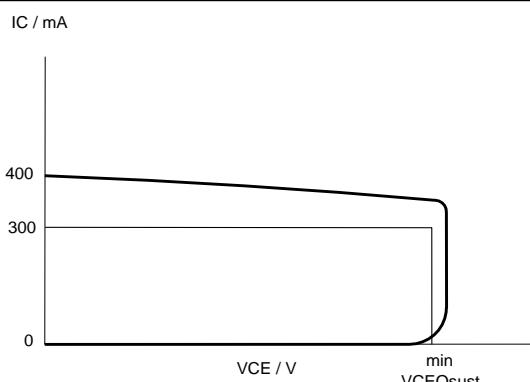
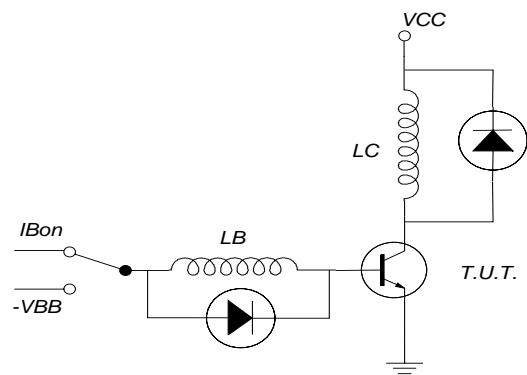
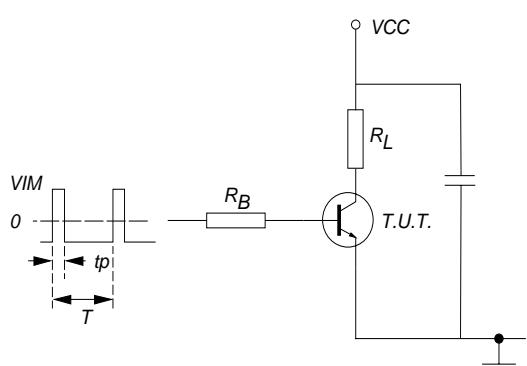
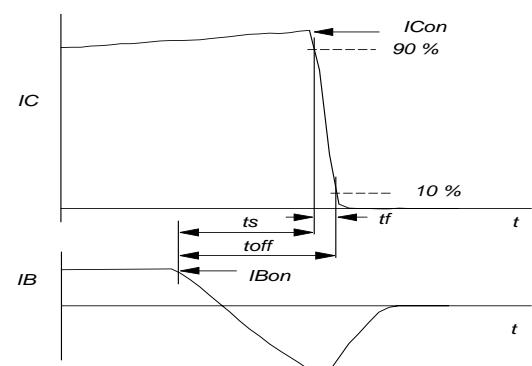
Fig.2. Oscilloscope display for  $V_{CEO_sust}$ .Fig.5. Test circuit inductive load.  
 $V_{CC} = 350\text{ V}$ ;  $-V_{BE} = 5\text{ V}$ ;  $L_C = 300\text{ }\mu\text{H}$ ;  $L_B = 1\text{ }\mu\text{H}$ Fig.3. Test circuit resistive load.  $V_{IM} = -6$  to  $+8\text{ V}$   
 $V_{CC} = 250\text{ V}$ ;  $t_p = 20\text{ }\mu\text{s}$ ;  $\delta = t_p/T = 0.01$ .  
 $R_B$  and  $R_L$  calculated from  $I_{C_{on}}$  and  $I_{B_{on}}$  requirements.

Fig.6. Switching times waveforms with inductive load.

## Silicon Diffused Power Transistor

BUJ303B

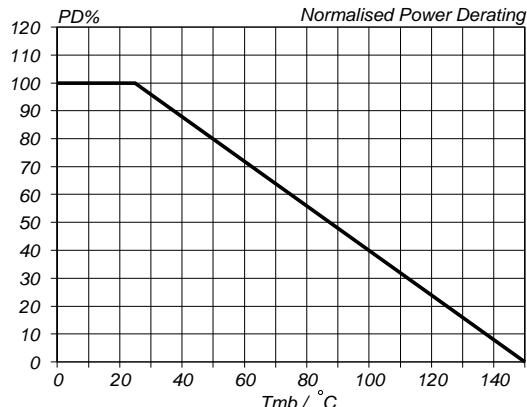


Fig.7. Normalised power dissipation.  
 $PD\% = 100 \cdot PD/PD_{25^\circ C} = f(T_{mb})$

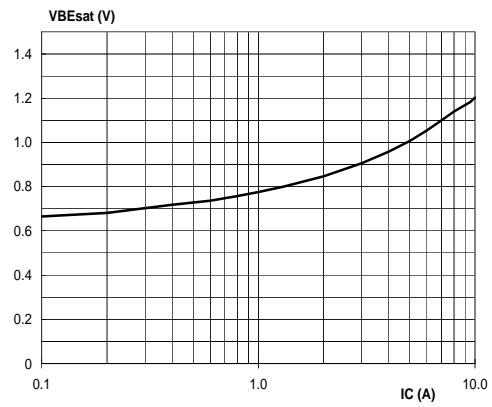


Fig.10. Base-Emitter saturation voltage.  
Solid lines = typ values,  $V_{BEsat} = f(IC)$ ; at  $IC/IB = 4$ .

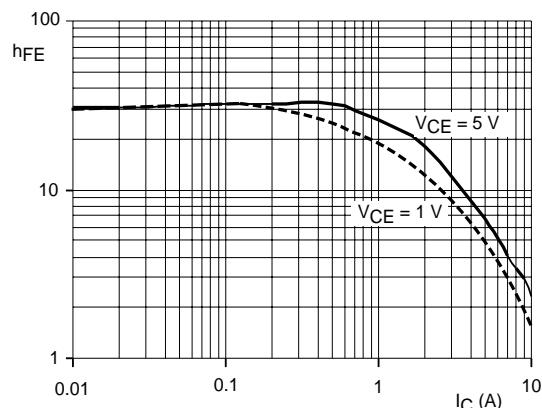


Fig.8. Typical DC current gain.  $h_{FE} = f(I_C)$   
parameter  $V_{CE}$

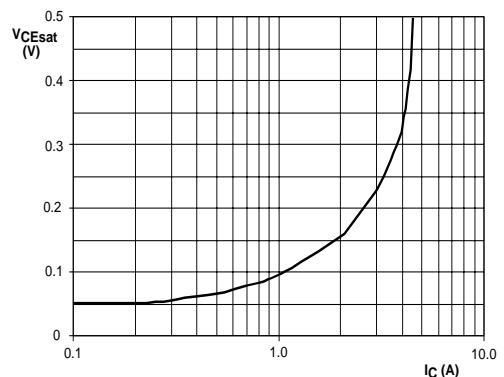


Fig.11. Collector-Emitter saturation voltage.  
Solid lines = typ values,  $V_{CEsat} = f(IC)$ ; at  $IC/IB = 4$ .

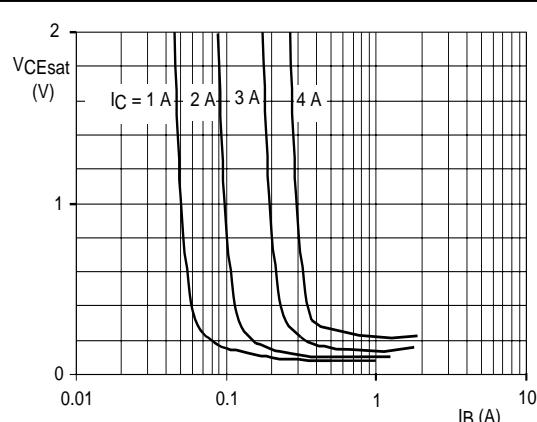


Fig.9. Collector-Emitter saturation voltage.  
Solid lines = typ values,  $V_{CEsat} = f(IB)$ ;  $T_j = 25^\circ C$ .

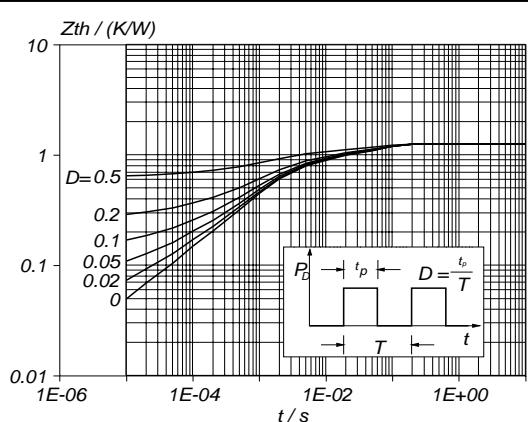


Fig.12. Transient thermal impedance.  
 $Z_{th,j-mb} = f(t)$ ; parameter  $D = t_p/T$

## Silicon Diffused Power Transistor

BUJ303B

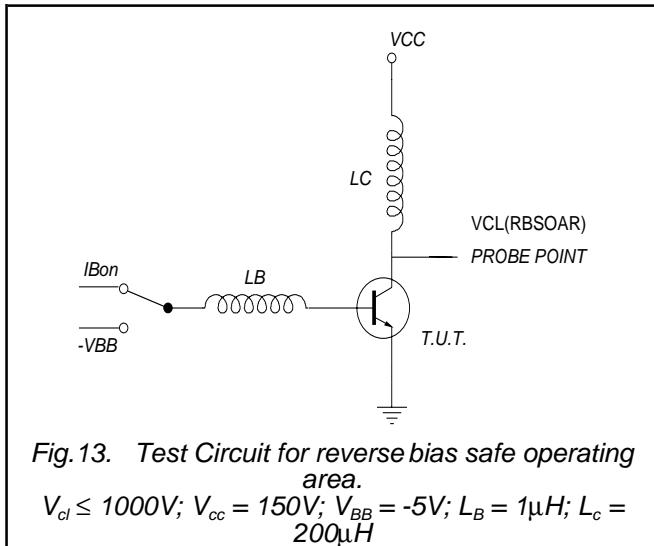


Fig.13. Test Circuit for reverse bias safe operating area.

$V_{cl} \leq 1000V$ ;  $V_{cc} = 150V$ ;  $V_{BB} = -5V$ ;  $L_B = 1\mu H$ ;  $L_c = 200\mu H$

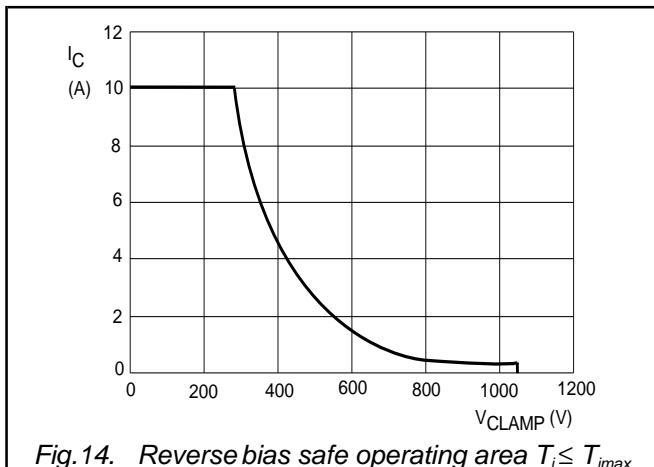


Fig.14. Reverse bias safe operating area  $T_j \leq T_{jmax}$

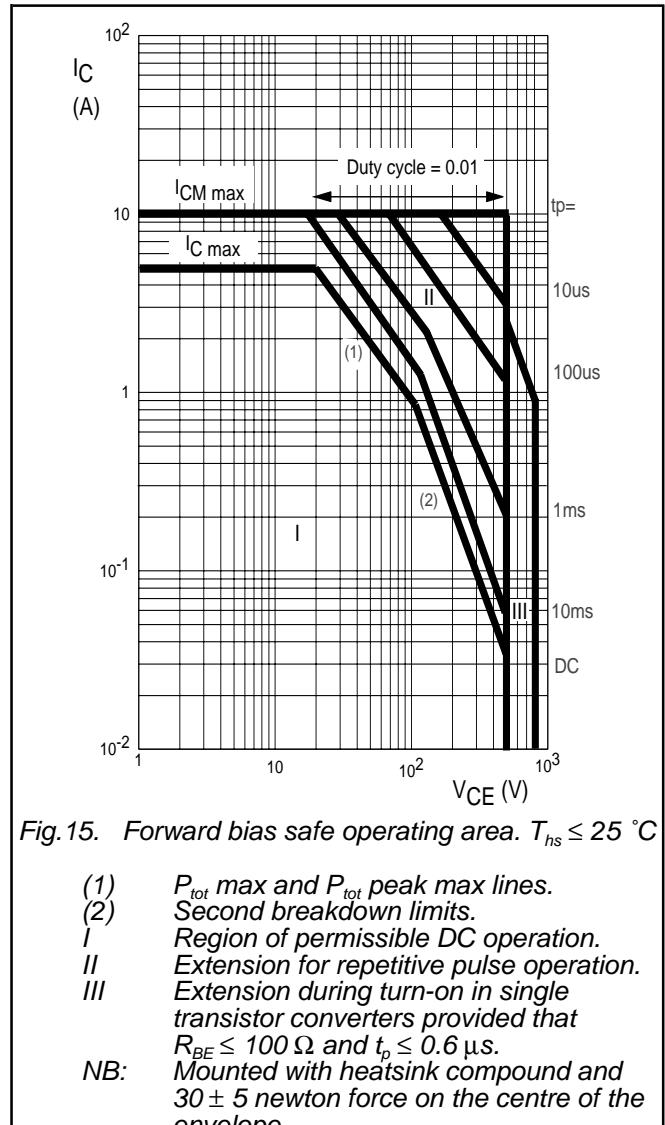


Fig.15. Forward bias safe operating area.  $T_{hs} \leq 25^\circ C$

- (1)  $P_{tot} \text{ max and } P_{tot} \text{ peak max lines.}$
- (2)  $\text{Second breakdown limits.}$
- I  $\text{Region of permissible DC operation.}$
- II  $\text{Extension for repetitive pulse operation.}$
- III  $\text{Extension during turn-on in single transistor converters provided that } R_{BE} \leq 100\Omega \text{ and } t_p \leq 0.6\mu s.$

NB: Mounted with heatsink compound and  $30 \pm 5$  newton force on the centre of the envelope.

## Silicon Diffused Power Transistor

BUJ303B

**MECHANICAL DATA***Dimensions in mm*

Net Mass: 2 g

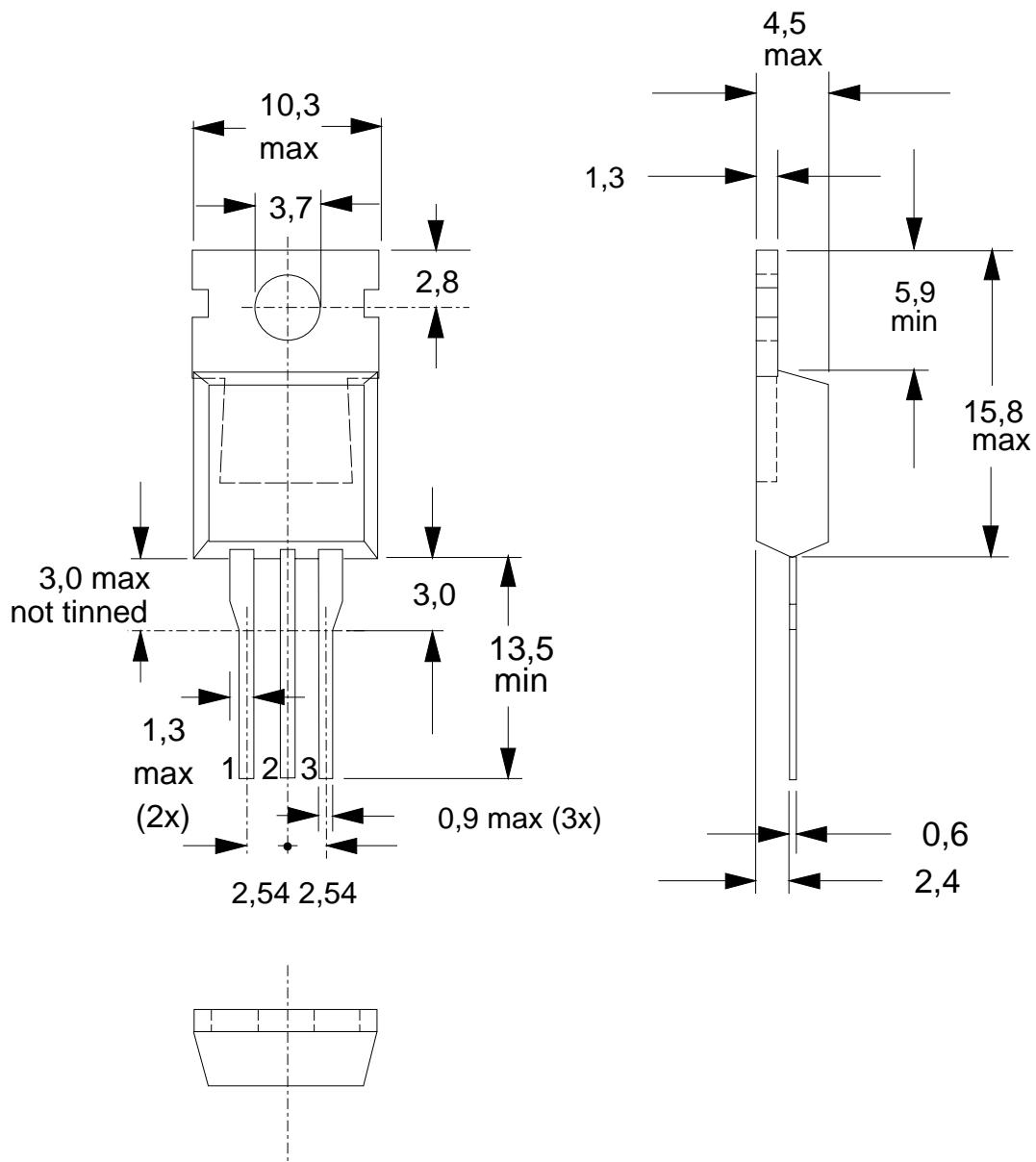


Fig. 16. TO220AB; pin 2 connected to mounting base.

**Notes**

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

**Silicon Diffused Power Transistor****BUJ303B****DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
<b>© Philips Electronics N.V. 2002</b>	
All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.	
The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.	

**LIFE SUPPORT APPLICATIONS**

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.